3.5x3.5 mm SMD CHIP LED LAMP

Part Number: AA3535QB25Z1S



ATTENTION

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Features

- White SMD package, silicone resin.
- Low thermal resistance.
- Compatible with IR-reflow processes.
- ESD protection.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 2a.
- RoHS compliant.

Descriptions

 The Blue source color devices are made with InGaN on Al₂O₃ substrate Light Emitting Diode.

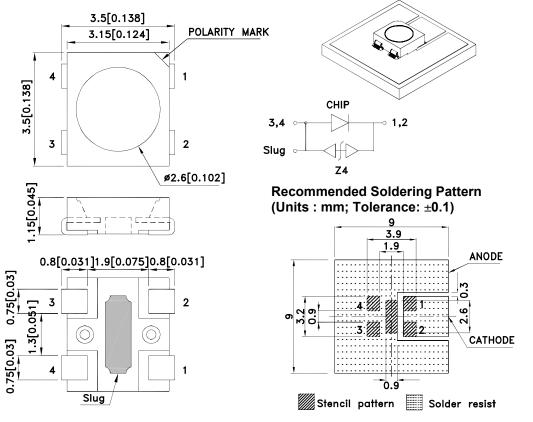
Blue

- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Applications

- Signal and symbol luminaire for orientation.
- Marker lights (e.g. steps, exit ways, etc).
- Decorative and entertainment lighting.
- Commercial and residential lighting.
- Automotive interior lighting.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

4. The device has a single mounting surface. The device must be mounted according to the specifications.





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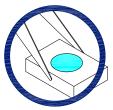
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Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

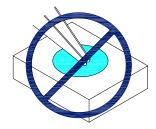
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

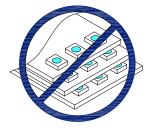


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

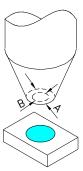




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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Selection Guide

Part No.	Dice	Lens Type	lv (cd) [2] @ 150mA		Фv (lm) [2] @ 150mA*		Viewing Angle [1]
			Min.	Тур.	Min.	Тур.	2 θ 1/2
AA3535QB25Z1S	Blue (InGaN)	Water Clear	0.7	1.3	2.4	3.5	120°

Notes:

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity/ luminous Flux: +/-15%.*LEDs are binned according to their luminous flux.
 3. Luminous intensity/ luminous Flux value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	Pb	600	mW
Junction Temperature [1]	TJ	130	°C
Operating Temperature	Тор	-40 To +85	°C
Storage Temperature	Tstg	-40 To +85	°C
DC Forward Current [1]	lF	150	mA
Peak Forward Current [2]	lғм	300	mA
Reverse Voltage	VR	5	V
Thermal Resistance [1] (Junction/ambient)	Rth j-a	180	°C/W
Thermal Resistance [1] (Junction/solder point)	Rth j-S	85	°C/W
Electrostatic Discharge Threshold (HBM)	8000	V	

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit	
Wavelength at peak emission IF=150mA [Typ.]	λ peak	445	nm	
Dominant Wavelength IF=150mA [Typ.]	λ dom [1]	450	nm	
Spectral Line Half-width IF=150mA [Typ.]	Δλ	20	nm	
Forward Voltage Ir=150mA [Min.]		2.7		
Forward Voltage Ir=150mA [Typ.]	VF [2]	3.5	V	
Forward Voltage IF=150mA [Max.]		4.0		
Allowable Reverse Current [Max.]	lr	85	mA	
Temperature coefficient of λ peak IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TC λ peak	0.12	nm/° C	
Temperature coefficient of λ dom IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TC λ dom	0.1	nm/° C	
Temperature coefficient of VF IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TCv	-2.3	mV/° C	

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^{1.}Results from mounting on PC board FR4(pad size ≥ 70mm²), mounted on pc board-metal core PCB is recommend for lowest thermal Resistance.

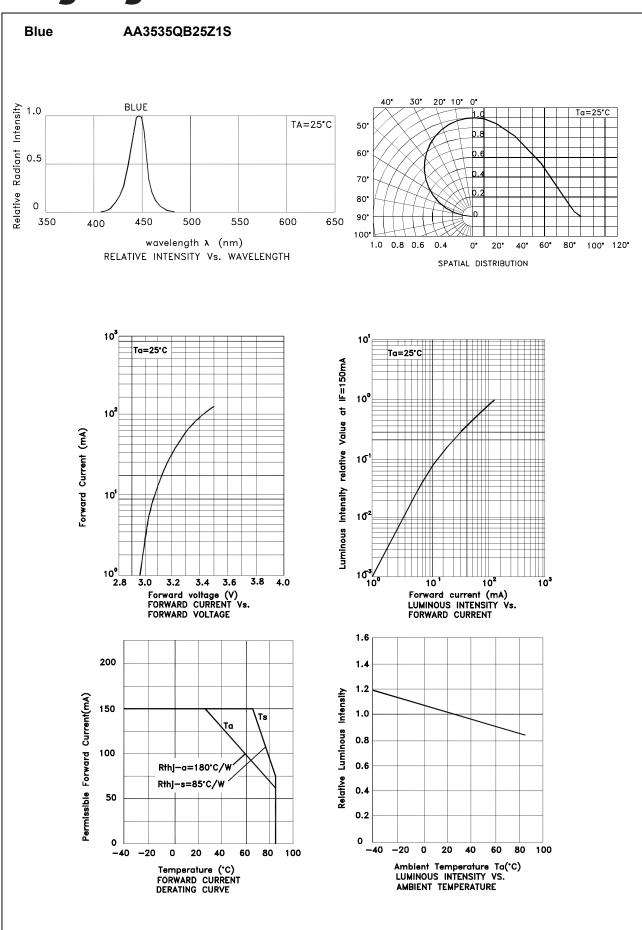
^{2.1/10} Duty Cycle, 0.1ms Pulse Width.

^{1.}Wavelength: +/-1nm.

^{2.}Forward Voltage: +/-0.1V.

^{3.} Wavelength value is traceable to the CIE127-2007 compliant national standards.

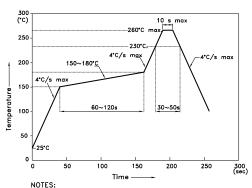
^{4.}Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.



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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



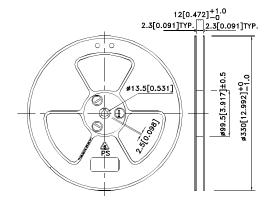
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

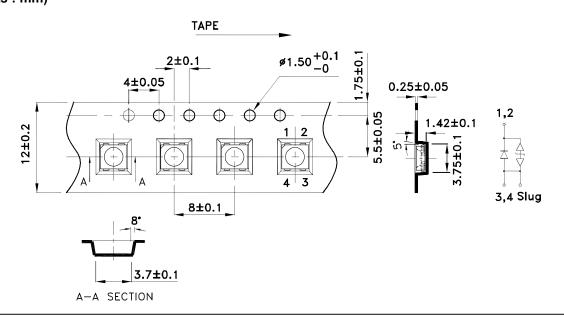
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.

3. Number of reflow process shall be 2 times or less.

Reel Dimension

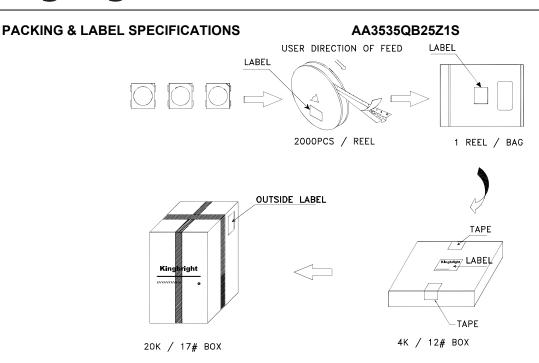


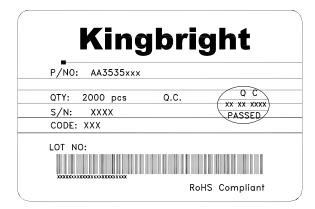
Tape Specifications (Units: mm)



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